

**MNLMH6702-X REV 1A0**

Original Creation Date: 01/16/04  
Last Update Date: 03/08/04  
Last Major Revision Date: 01/30/04

**Ultra Low Distortion, Current Feedback Widedband OP  
AMP**

**General Description**

The LMH6702 is a very wideband, DC coupled monolithic operational amplifier designed specifically for wide dynamic range systems requiring exceptional signal fidelity. Benefiting from National's current feedback architecture, the LMH6702 offers a unity gain stability at exceptional speed without need for external compensation.

With its 720MHz bandwidth ( $A_v = 2V/V$ ,  $V_o = 2V_{pp}$ ), 10-bit distortion levels through 600MHz ( $R_l = 100 \text{ Ohms}$ ), 1.83nV/SqRtHz input referred noise and 12.5mA supply current, the LMH6702 is the ideal driver or buffer for high-speed flash A/D and D/A converters.

Wide dynamic range systems such as radar and communication receivers requiring a wideband amplifier offering exceptional signal purity, will find the LMH6702's low input referred noise and low harmonic and intermodulation distortion make it an attractive high speed solution.

The LMH6702 is constructed using National's VIP10 (TM) complimentary bipolar process and National's proven current feedback architecture.

**Industry Part Number**

LMH6702

**NS Part Numbers**

LMH6702J-QML  
LMH6702WG-QML

**Prime Die**

LMH6702

**Controlling Document**

SEE FEATURES SECTION

**Processing**

MIL-STD-883, Method 5004

**Quality Conformance Inspection**

MIL-STD-883, Method 5005

Subgrp	Description	Temp ( °C)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55

**Features**

Vs =  $\pm 5V$ , Ta = 25 Degree C, Av = +2V/V, Rl = 100 Ohms, Vout = 2Vpp, Typical unless Noted:

- -3dB Bandwidth (Vout = 2Vpp) 720MHz
- Low Noise 1.83nV/SqRtHz
- Fast settling to 0.1% 13.4ns
- Fast slew rate 3100V/uS
- Supply current 12.5mA
- Output current 80mA
- Low Intermodulation Distortion (75MHz) -67dBc
- Improved Replacement for CLC409 and CLC449

CONTROLLING DOCUMENTS:

LMH6702J-QML	5962-0254601QPA
LMH6702WG-QML	5962-0254601QZA

**Applications**

- Flash A/D driver
- D/A transimpedance buffer
- Wide dynamic range IF amp
- Radar/communication receivers
- Line driver
- High resolution video

**(Absolute Maximum Ratings)**

(Note 1)

Supply Voltage (Vcc)	±6.75Vdc
Common Mode Input Voltage (Vcm)	V- to V+
Power Dissipation (Pd) (Note 2)	1W
Junction Temperature (Tj)	+175 C
Lead Temperature (soldering, 10 seconds)	+300 C
Storage Temperature Range	-65 C ≤ Ta ≤ +150 C
Thermal Resistance	
ThetaJA (Junction to Ambient)	
CERAMIC DIP (Still Air)	170 C/W
(500LF/Min Air Flow)	100 C/W
CERAMIC SOIC (Still Air)	220 C/W
(500LF/Min Air Flow)	150 C/W
ThetaJC (Junction to Case)	
CERAMIC DIP	35 C/W
CERAMIC SOIC	37 C/W
Package Weight (Typical)	
CERAMIC DIP	1078 mg
CERAMIC SOIC	227 mg
ESD Tolerance (Note 3)	1000V

- Note 1: Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- Note 2: The maximum power dissipation must be derated at elevated temperatures and is dictated by Tjmax (maximum junction temperature), ThetaJA (package junction to ambient thermal resistance, and TA (ambient temperature). The maximum allowable power dissipation at any temperature is Pdmax = (Tjmax - TA)/ThetaJA or the number given in the Absolute Maximum Ratings, whichever is lower.
- Note 3: Human body model, 1.5K Ohms in series with 100pF.

### **Recommended Operating Conditions**

Supply Voltage (Vcc)	$\pm 5\text{Vdc}$ to $\pm 6\text{Vdc}$
Gain Range	$\pm 1$ to $\pm 10$
Ambient Operating Temperature Range (Ta)	-55 C to +125 C

## Electrical Characteristics

### DC PARAMETERS

(The following conditions apply to all the following parameters, unless otherwise specified.)  
 DC:  $R_l = 100 \text{ Ohms}$ ,  $V_{cc} = \pm 5\text{Vdc}$ ,  $A_v = +2$  feedback resistor ( $R_f$ ) = 250 Ohms, gain resistor ( $R_g$ ) - 250  
 (NOTE 1)

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
Ibn	Input Bias Current, Noninverting				-15	+15	uA	1, 2
					-21	+21	uA	3
Ibi	Input Bias Current, Inverting				-30	+30	uA	1, 2
					-34	+34	uA	3
Vio	Input Offset Voltage				-4.5	+4.5	mV	1, 3
					-6.0	+6.0	mV	2
Icc	Supply Current, no load	$R_l = \text{infinity}$				15	mA	1, 2, 3
PSSR	Power Supply Rejection Ratio	$-V_{cc} = -4.5\text{V to } -5.0\text{V}$ , $+V_{cc} = +4.5\text{V to } +5.0\text{V}$			45		dB	1, 2, 3

### AC PARAMETERS

(The following conditions apply to all the following parameters, unless otherwise specified.)  
 AC:  $R_l = 100 \text{ Ohms}$ ,  $V_{cc} = \pm 5\text{Vdc}$ ,  $A_v = +2$  feedback resistor ( $R_f$ ) = 250 Ohms, gain resistor ( $R_g$ ) - 250  
 (NOTE 1)

HD3	3rd Harmonic Distortion	2Vpp at 20MHz				-62	dBc	4
GFPL	Gain Flatness Peaking	0.1MHz to 75MHz, $V_{out} < 0.5V_{pp}$				0.4	dB	4
GFPH	Gain Flatness Peaking	> 75MHz, $V_{out} < 0.5V_{pp}$				2.0	dB	4
GFRH	Gain Flatness Rolloff	75MHz to 125MHz, $V_{out} < 0.5V_{pp}$				0.2	dB	4
HD2	2nd Harmonic Distortion	2Vpp at 20MHz				-52	dBc	4

Note 1: The algebraic convention, whereby the most negative value is a minimum and most positive is a maximum, is used in this table. Negative current shall be defined as conventional current flow out of a device terminal.

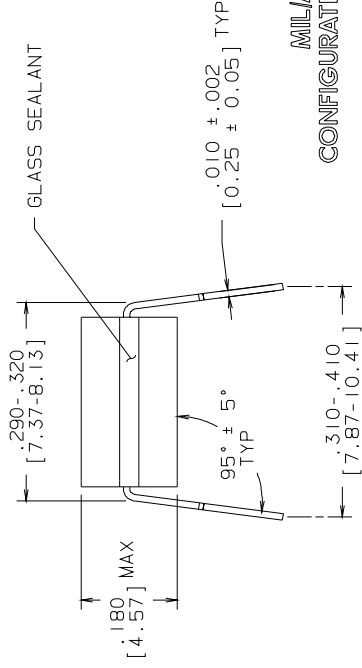
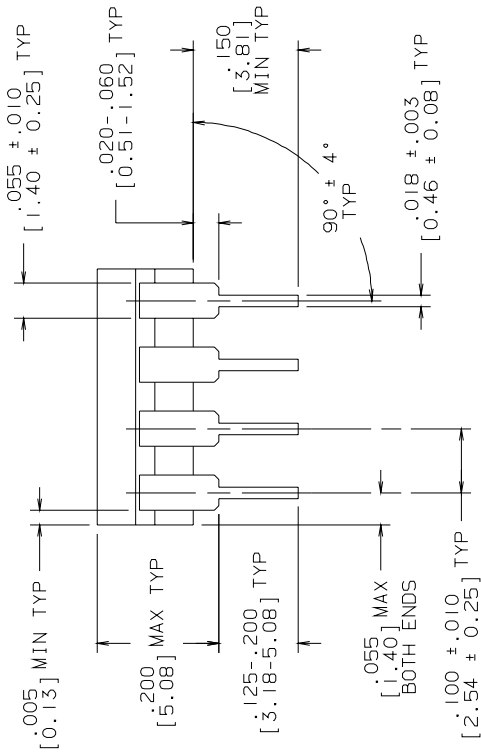
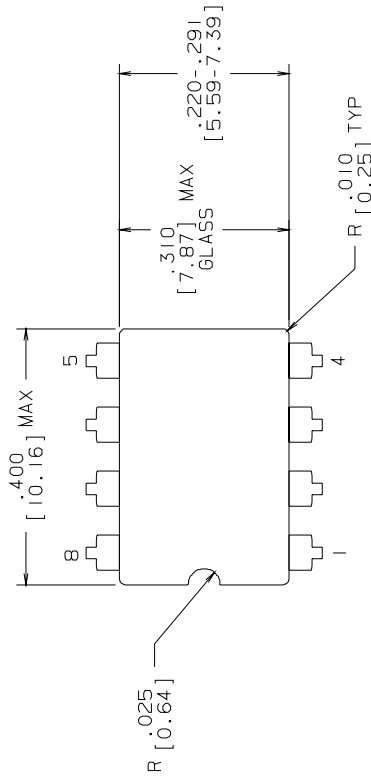
## Graphics and Diagrams

GRAPHICS#	DESCRIPTION
06409HRA3	CERAMIC SOIC (WG), 10 LEAD (B/I CKT)
07077HRA5	CERDIP (J), 8 LEAD (B/I CKT)
J08ARL	CERDIP (J), 8 LEAD (P/P DWG)
P000481A	CERDIP (J), 8 LEAD (PIN OUT)
P000485A	CERAMIC SOIC (WG), 10 LEAD (PIN OUT)
WG10ARC	CERAMIC SOIC (WG), 10 LEAD (P/P DWG)

See attached graphics following this page.

REV I S I O N S

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
L	REVISE PER CURRENT STD; REDRAW	10002	09/21/93	TL/



MILAERO  
 CONFIGURATION CONTROL  
 MIL-M-38510  
 CONFIGURATION CONTROL

CONTROLLING DIMENSION: INCH

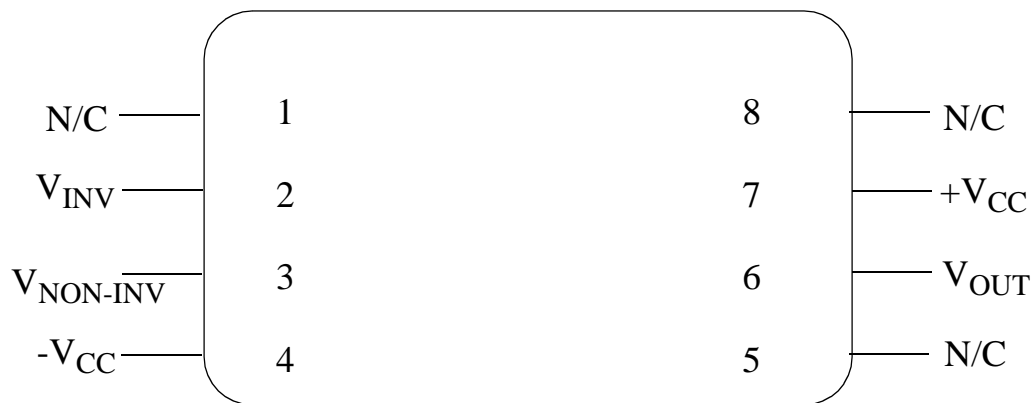
APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION
DRAWN <b>T. LEQUANG</b>	09/21/93	2900 Semiconductor Drive, Santa Clara, CA 95052-8090
DFTG. CHK.		
ENGR. CHK.		
APPROVAL		

CERDIP (J),  
 8 LEAD

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	B	MKT-J08A	L
	DO NOT SCALE DRAWING	SHEET	OF	

NOTES: UNLESS OTHERWISE SPECIFIED

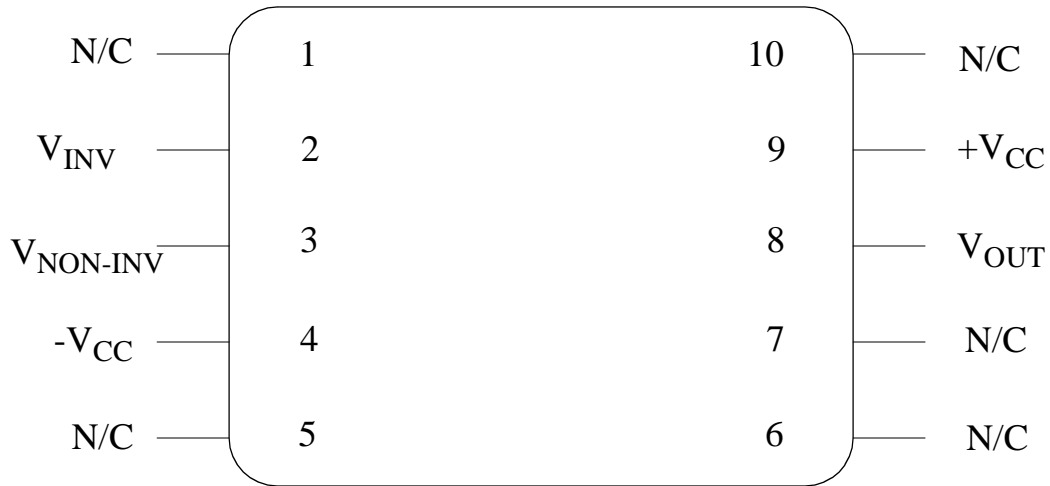
- LEAD FINISH TO BE 200 MICROMETERS / 5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
- JEDEC REGISTRATION MO-036, VARIATION AA, DATED 04/1981.



LMH6702J  
8 - LEAD DIP  
CONNECTION DIAGRAM  
TOP VIEW  
P000481A



National Semiconductor™  
MIL/AEROSPACE OPERATIONS  
2900 SEMICONDUCTOR DRIVE  
SANTA CLARA, CA 95050



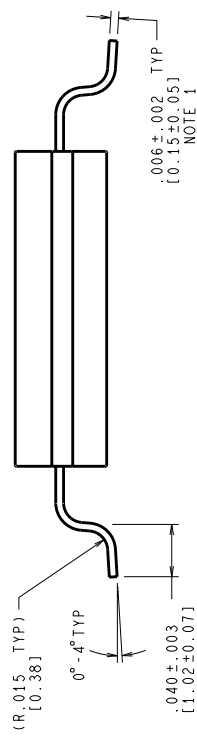
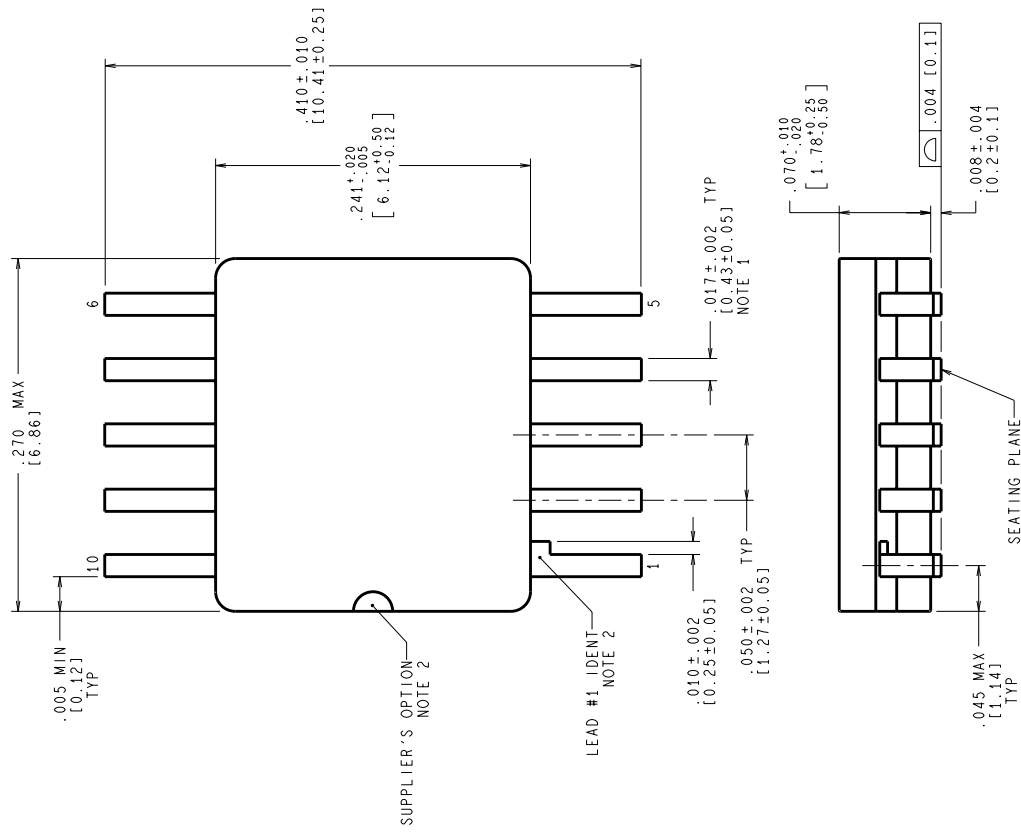
**LMH6702WG**  
**10 - LEAD CERAMIC SOIC**  
**CONNECTION DIAGRAM**  
**TOP VIEW**  
**P000485A**



National Semiconductor™  
MIL/AEROSPACE OPERATIONS  
2900 SEMICONDUCTOR DRIVE  
SANTA CLARA, CA 95050

REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11374	02/29/1996	MS/KH
B	LD PITCH TOL WAS ±.005; CHANGE LD RADIUS TO REF DIM; REMOVE THE OTHER R.006±.002 DIM. .040±.003 WAS .037±.003	11441	04/19/1996	MS/KH
C	R .015(0.38) WAS R .006(0.15)	11838	10/08/1997	TL/



CONTROLLING DIMENSION IS INCH  
VALUES IN | ARE MILLIMETERS

MIL-PRF-38535  
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICRONS/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE. MAXIMUM LIMIT MAY BE INCREASED BY .003 IN/ 0.08mm AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
  - A NOTCH OR OTHER MARK WITHIN THIS AREA
  - A TAB ON LEAD 1, EITHER SIDE
- NO JEDEC REGISTRATION AS OF FEBRUARY 1996.

APPROVALS	DATE	SCALE	SIZE	DRAWING NUMBER	REV
DRN: MARYA SUCHY	02/29/96	N/A	C	(SC)MKT-WG10A	C
DATE: 02/29/96					
CHK: [Signature]					
CHK: [Signature]					
PROJECTION					
DO NOT SCALE DRAWING					
SHEET 1 of 1					

**National Semiconductor**  
2800 Semiconductor Dr., Santa Clara, CA 95052-8090

**CERPACK,  
10 LEAD,  
GULL WING**

**Revision History**

Rev	ECN #	Rel Date	Originator	Changes
0A0	M0004358	03/08/04	Rose Malone	Initial MDS Release: MNLHM6702-X, Rev. 0A0
1A0	M0004360	03/08/04	Rose Malone	Update MDS: MNLHM6702-X, Rev. 0A0 to MNLHM6702-X, Rev. 1A0. Added reference to Controlling Documents in Features Section. Changed the following Parameter limits on: Ibn, Ibi, Vio, Icc, HD3, GFPH and GFRH.